

## **LCLS-II FUNDAMENTAL POWER COUPLER MECHANICAL INTEGRATION**

Details of thermal straps, connections, and other interfaces

K. Premo, T. Arkan, Y. Orlov, N. Solyak

Fermi National Accelerator Laboratory, Batavia, IL 60510, USA





## Modifications/Design changes (differences from TTF3)

- Cold end
- Antenna length shortened by 8.5mm
- CF100 55K interface mounting surface increased
- Diameter increased from 64mm-78mm, mounting area almost doubled
- Bolt size increased from M4 to M6 to improve clamping force (> 2x)
- Holes for temperature sensors added to CF100 flange
- Warm end
- Increased Cu plating thickness on inner conductor
- Increased from 30 micron to 150 micron to reduce bellows temperature
- Additional threaded hole to be added for transportation support



## Thermal interfaces to cryomodule

- Location of thermal intercepts on the couplers has not changed from TTF3 type
- There are two coupler thermal interfaces to cryomodule
- 5K intercept on cold end (between bellows and cavity flange)
- 55K intercept on cold end CF100 flange
- CW operation requires improved heat transfer away from coupler, from both the 5K and 55K intercepts









Thermal interfaces to cryomodule

- 55K intercept interface design
- Design concept similar to ILC type and XFEL
- Interface consists of aluminum shield bolted to back of CF100 flange using M6 screws
- Design will use high performance engineered OFHC Cu straps
- 2 straps take heat to 55K outer shield
- Bolted connections will utilize indium for better thermal contact

## 5K intercept

- Interface design
- 5K coupler interface clamped to coupler intercept (copper ring)
- Design will use high performance engineered OFHC Cu straps
- 2 Cu straps take heat to 5K line via bolted connection
- Connections will utilize indium for better thermal contact





\* Work supported, in part, by Fermi Research Alliance, LLC under Contract No. DE-AC02-07CH11359 with the United States Department of Energy, and the LCLS-II Project